



Material Content Data Sheet



Sales Product Name		BSD235C H6327		Issued		24. January 2018		
MA#		MA001634758						
Package		PG-SOT363-6-1		Weight*		6.29 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.002	0.04		394	
	noble metal	gold	7440-57-5	0.010	0.15		1529	
	inorganic material	silicon	7440-21-3	0.128	2.03	2.22	20326	22249
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		92	
	non noble metal	titanium	7440-32-6	0.003	0.05		458	
	non noble metal	chromium	7440-47-3	0.009	0.14		1374	
	non noble metal	copper	7440-50-8	2.869	45.58	45.78	455902	457826
wire	non noble metal	copper	7440-50-8	0.011	0.17	0.17	1689	1689
encapsulation	organic material	carbon black	1333-86-4	0.030	0.48		4754	
	plastics	epoxy resin	-	0.643	10.22		102216	
	inorganic material	silicondioxide	60676-86-0	2.319	36.85	47.55	368452	475422
leadfinish	non noble metal	tin	7440-31-5	0.213	3.39	3.39	33882	33882
plating	noble metal	silver	7440-22-4	0.056	0.89	0.89	8932	8932
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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